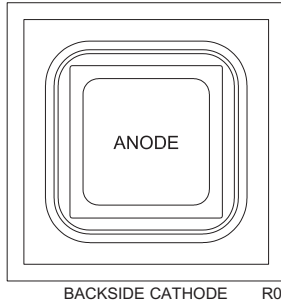


**CPZ59X-CMPZ5246B THRU
CPZ59X-CMPZ5267B
Zener Diode Die
500mW, 16 THRU 75 VOLT**

The CPZ59X-CMPZ5246B thru CPZ59X-CMPZ5267B are silicon Zener diodes ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	13 x 13 MILS
Die Thickness	5.5 MILS
Anode Bonding Pad Size	5.9 x 5.9 MILS
Top Side Metalization	Al – 20,000Å
Back Side Metalization	Au-As – 12,000Å
Scribe Alley Width	1.67 MILS
Wafer Diameter	6 INCHES
Gross Die Per Wafer	145,998

MAXIMUM RATINGS:

Operating and Storage Junction Temperature

SYMBOL

T_J, T_{stg}

-65 to +150

UNITS

°C

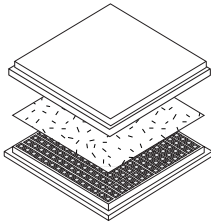
ELECTRICAL CHARACTERISTICS: ($T_A=25^{\circ}\text{C}$) $V_F=1.2\text{V MAX @ } I_F=200\text{mA}$ (for all types)

TYPE	ZENER VOLTAGE $V_Z @ I_{ZT}$			TEST CURRENT	MAXIMUM ZENER IMPEDANCE			MAXIMUM REVERSE CURRENT		MAXIMUM TEMPERATURE COEFFICIENT
	MIN	NOM	MAX	I_{ZT}	$Z_{ZT} @ I_{ZT}$	$Z_{ZK} @ I_{ZK}$	$I_R @ V_R$			
	V	V	V	mA	Ω	Ω	μA	V		%/°C
CPZ59X-CMPZ5246B	15.20	16	16.80	7.8	17	600	0.25	0.1	12	+0.083
CPZ59X-CMPZ5247B	16.15	17	17.85	7.4	19	600	0.25	0.1	13	+0.084
CPZ59X-CMPZ5248B	17.10	18	18.90	7.0	21	600	0.25	0.1	14	+0.085
CPZ59X-CMPZ5249B	18.05	19	19.95	6.6	23	600	0.25	0.1	14	+0.086
CPZ59X-CMPZ5250B	19.00	20	21.00	6.2	25	600	0.25	0.1	15	+0.086
CPZ59X-CMPZ5251B	20.90	22	23.10	5.6	29	600	0.25	0.1	17	+0.087
CPZ59X-CMPZ5252B	22.80	24	25.20	5.2	33	600	0.25	0.1	18	+0.088
CPZ59X-CMPZ5253B	23.75	25	26.25	5.0	35	600	0.25	0.1	19	+0.089
CPZ59X-CMPZ5254B	25.65	27	28.35	4.6	41	600	0.25	0.1	21	+0.090
CPZ59X-CMPZ5255B	26.60	28	29.40	4.5	44	600	0.25	0.1	21	+0.091
CPZ59X-CMPZ5256B	28.50	30	31.50	4.2	49	600	0.25	0.1	23	+0.091
CPZ59X-CMPZ5257B	31.35	33	34.65	3.8	58	700	0.25	0.1	25	+0.092
CPZ59X-CMPZ5258B	34.20	36	37.80	3.4	70	700	0.25	0.1	27	+0.093
CPZ59X-CMPZ5259B	37.05	39	40.95	3.2	80	800	0.25	0.1	30	+0.094
CPZ59X-CMPZ5260B	40.85	43	45.15	3.0	93	900	0.25	0.1	33	+0.095
CPZ59X-CMPZ5261B	44.65	47	49.35	2.7	105	1000	0.25	0.1	36	+0.095
CPZ59X-CMPZ5262B	48.45	51	53.55	2.5	125	1100	0.25	0.1	39	+0.096
CPZ59X-CMPZ5263B	53.20	56	58.80	2.2	150	1300	0.25	0.1	43	+0.096
CPZ59X-CMPZ5264B	57.00	60	63.00	2.1	170	1400	0.25	0.1	46	+0.097
CPZ59X-CMPZ5265B	58.90	62	65.10	2.0	185	1400	0.25	0.1	47	+0.097
CPZ59X-CMPZ5266B	64.60	68	71.40	1.8	230	1600	0.25	0.1	52	+0.097
CPZ59X-CMPZ5267B	71.25	75	78.75	1.7	270	1700	0.25	0.1	56	+0.098

Note: V_Z Tolerance is $\pm 5\%$

R0 (14-August 2023)

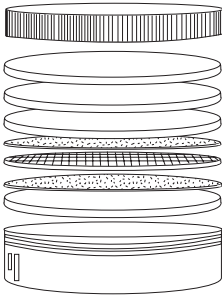
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

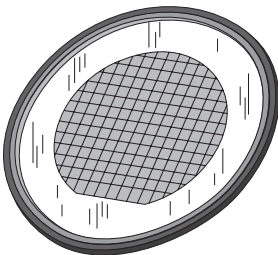
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

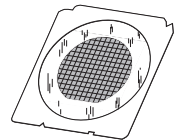
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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